

**Serial No. 10/692,403**  
**Atty. Doc. No. 2003P14606US**

**Amendments to the Specification**

On page 12, please amend the abstract as follows:

--A joint (32) having bond line grains (28) that nucleate in the joint region (32) and grow into the adjoined solid substrates (12, 14). The resulting bond line grains have a size that is greater than a thickness (T) of a molten region (15). The surfaces of the substrates are cold worked to a desired degree of residual stress prior to the bonding process so that the recrystallization of the substrate surface necessary for the grains to grow into the substrates results in a reduction in the local free energy.--